

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	10	(power adj semiconductor adj module) and (metal adj base) and (ceramic adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:03
S2	144	kobayashi-takatoshi.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 13:52
S3	926	(power adj semiconductor adj module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:16
S4	28	(power adj module) and (metal adj base) and (ceramic adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:06
S5	441	(metal adj base) and (ceramic adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:16
S6	108	(power adj module) and (metal adj plate) and (ceramic adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:06
S7	1212	(metal adj plate) and (ceramic adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:17
S8	214	(metal adj plate) and (ceramic adj substrate) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:15

S9	86	(metal adj base) and (ceramic adj substrate) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:16
S10	166	(power adj semiconductor adj module) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:16
S11	99	(metal adj plate) and (ceramic adj substrate) and casting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:19
S12	30	(metal adj base) and (ceramic adj substrate) and casting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:20
S13	1	(power adj module) and (metal adj base) and (ceramic adj substrate) and casting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:20
S14	155	(power adj module) and casting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:20
S15	26	(power adj semiconductor adj module) and casting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:21
S16	552	(metal adj plate) and (ceramic adj substrate) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:21

S17	223	(metal adj base) and (ceramic adj substrate) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:22
S18	17	(power adj module) and (metal adj base) and (ceramic adj substrate) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:22
S19	1811	(power adj module) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:23
S20	285	(power adj semiconductor adj module) and (chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:23
S21	30	(metal adj plate) and (ceramic adj substrate) and (circuit adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:22
S22	17	(metal adj base) and (ceramic adj substrate) and (circuit adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:22
S23	0	(power adj module) and (metal adj base) and (ceramic adj substrate) and (circuit adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:22
S24	6	(power adj semiconductor adj module) and (circuit adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:23

S25	96	(power adj module) and (circuit adj assembly)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 14:23
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